WHAT IS CLAIMED IS:

1. A process for producing a cured film having the memory of a specified shape, which process comprises shaping a resin composition by either applying it onto a shaped part or placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films, said resin composition comprising:

(a) an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature, Tg, of lower than 50°C after polymerization; and

(b) a low-molecular weight compound that has in its molecule one reactive double bond capable of polymerization with the oligomer compound (a) and that has a glass transition temperature, Tg, higher than at least 90°C after polymerization; or

(b') a mixture of two or more low-molecular weight compounds that have in their molecule one reactive double bond capable of copolymerization with the oligomer compound (a) and that have a glass transition temperature, Tg, higher than 90°C after polymerization.

2. A process for producing a cured film having the memory of a specified shape, which process comprises shaping a resin composition by either applying it onto a shaped part or placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films, said. resin composition comprising:

(a) an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature, Tg, lower than 50°C after polymerization;

(b) a simple urethane adduct of hydroxyethyl acrylate or hydroxyethyl methacrylate and a diisocyanate; and

(c) an optional low-molecular weight compound that has in its molecule at least one double bond capable of copolymerization with the oligomer compound (a).